



## —Low Dk and Df— Coverlay "C23"

### Example of use

- 5G phone
- Base station antenna
- ADAS (Advanced Driver-Assistance Systems)



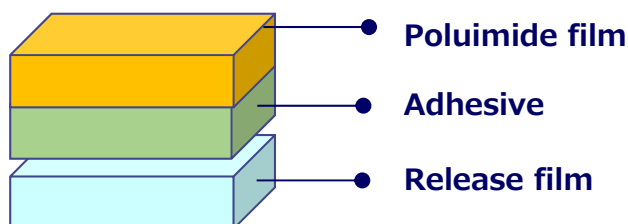
### Characteristics

- Low Dielectric constant & Low Dissipation factor.  
Dk : 2.4, Df : 0.003 @10GHz

### Appearance



### Product structure

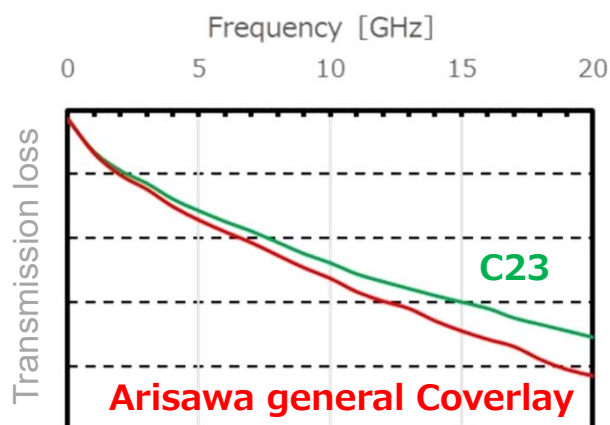


### Product Properties

Item	Unit	C23	
Polyimide film thickness	μm	12.5	
Adhesive thickness	μm	25	
Dk (10GHz)	Coverlay	-	2.75
	Adhesive only	-	2.43
Df (10GHz)	Coverlay	-	0.005
	Adhesive only	-	0.003
90°Peel strength (Peel PI)	N/cm	5.5	
Solder heat resistance (Float in solder bath for 30 sec.)	-	No problem	

Sample making condition (pressing) : 160°C×3MPa×60min

### <Transmission loss>



Impedance: 50Ω  
Circuit width: 55μm  
Circuit thickness: 12μm

### Test sample structure

